



PATENT

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June 26, 2001

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ohn Signature

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Art Unit: Examiner: 2856 HOLOGY CENTER 2800

Date

| ln | re | арр | lication | of: |
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Seiichi MORI

Serial No: 09,456,873

Filed:

December 8, 1999

For: NON-VOLATILE SEMICONDUCTOR MEMORY DEVICE

Box NON-FEE AMENDMENT Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

Transmitted herewith is an amendment in the above-identified application.

Small entity status of this application under 37 C.F.R. 1.9 and 1.27 hag been established by a verified statement previously submitted.

A verified statement to establish small entity status under 37 C.F.R. 1.9 and 1.27 is enclosed.

A Notice Of Change Of Attorney's Address and Associate Power Of Attorney is enclosed.

No additional fee is required.

The fee has been calculated as shown below:

| | (Col. 1) CLAIMS REMAINING AFTER AMENDMENT | | (Col. 2) HIGHEST NUMBER PREVIOUSLY PAID FOR | | (Col. 3) PRESENT EXTRA* | LG/SM \$ ENTITY FEE | | ADD'L FEE DUE | |
|--|---|---|---|-----|-------------------------------|------------------------|------|------------------|---|
| TOTAL CLAIMS FEE | 18 | - | 20 | ** | 0 | LG=\$18 SM=\$9 | \$18 | \$ | 0 |
| INDEPENDENT CLAIMS FEE | 5 | - | 5 | *** | 0 | LG=\$80 SM=\$40 | \$80 | \$ | 0 |
| FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIMS LARGE ENTITY FEE = \$270 SMALL ENTITY FEE = \$135 | | | | | | | | \$ | 0 |
| | | | | | | T | OTAL | \$ | 0 |

If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.

If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.

If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space. The "Highest Number Previously Paid For" (Total or Independent) is the highest number found from the equivalent box on Col. 1 of a prior amendment or the number of claims originally filed.

A check in the amount of \$___ to cover the additional claims fee is enclosed. A copy of this sheet is enclosed.

A check in the amount of \$__to cover the extension fee is enclosed. A copy of this sheet is enclosed. The Commissioner is hereby authorized to charge any deficiencies of fees associated with this communication or credit any overpayment to Deposit Account No. 50-1314. A copy of this sheet is enclosed.

Any filing fees under 37 C.F.R. 1.16 for the presentation of extra claims

Any patent application processing fees under 37 C.F.R. 1.17

Date: June 26, 2001

Biltmore Tower

500 South Grand Avenue, Suite 1900

Telephone: 213 337-6700 Facsimile: 213 337-6701

Respectfully submitted, HOGAN & HARTSØN L.L.P.

John P. Scherlacher

Régistration No. 23,009 Attorney for Applicant(s)

005702-20053 (8178

PATENT AND TRADEMARK OFFICE IN THE UNITED TECHNOLOGY CENTER 2800

In re application of:

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MEMORY DEVICE

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Examiner: Andujar, L.

Art Unit:

Seherlacher, Reg. No. 23,009

Signatyre

Date

AMENDMENT

Box Non-Fee Amendment Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated March 28, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Rewrite claim 1 as follows:

A non-volatile semiconductor memory device comprising: 1.

a semiconductor substrate; and

a memory cell having a floating gate provided through a tunnel

insulating layer on said semiconductor substrate, and a control gate provided

through an inter-layer insulating layer on said floating gate;

wherein said inter-insulating layer includes:

a silicon oxide later contiguous to said floating gate;